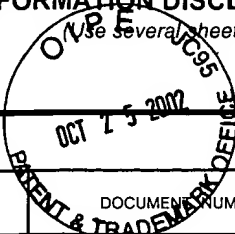


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JP	1.	3,620,714	11/16/71	Short	75	.5	
	2.	3,717,481	02/20/73	Short	106	1	
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	4.	3,768,994	10/30/73	Daiga	75	.5	
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	8.	4,020,206	04/26/77	Beil	428	137	
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JP	25.	Fievet et al., "Preparing Monodisperse Metal Powders in Micrometer and Submicrometer Sizes by the Polyol Process", MRS Bulletin, pp. 29-34, December 1989.
JP	26.	Getty et al., "High Performance Thick Film Gold Conductors", International Journal for Hybrid Microelectronics, Vol. 5, No. 2, pp. 487-495, November 1982.

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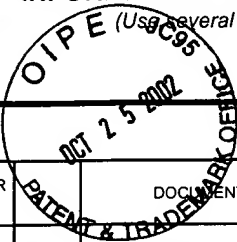
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DN	12. 4,326,889	04/27/82	Sperner	106	35	
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DN	27.	Majumdar et al., "Gold Particle Generation by Spray Pyrolysis", Adv. Mater., Vol. 8, No. 12., pp. 1020-1022, 1996.
DN	28.	Seshadri et al., "Preparation of Monodispersed, Submicron Gold Particles", Materials Research Bulletin, Vol. 29, No. 7, pp. 795-799, 1994

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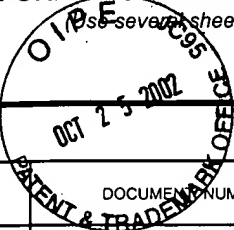
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PM	30.	Silvert et al., "Synthesis of Monodisperse Submicronic Gold Particles by the Polyol Process", Solid State Ionics, Vol. 82, pp. 53-60, 1995

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